

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Previously Presented): A heat conductive silicone rubber composite sheet, comprising:

a laminated structure with an intermediate layer and a pair of outer layers laminated to both surfaces of said intermediate layer, wherein

(A) said intermediate layer is a layer of a synthetic resin film that displays heat resistance and electrical insulation, and

(B) said outer layers are silicone rubber layers formed by curing a composition comprising (a) an organopolysiloxane, (b) a curing agent, (c) a heat conductive filler, and (d) a silicon compound-based adhesion imparting agent with at least one functional group selected from the group consisting of epoxy groups, alkoxy groups, vinyl groups, and the group represented by the formula Si-H;

wherein said curing agent of said component (b) is an organic peroxide.

Claim 2 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein the thickness of said synthetic resin film is within a range from 5 to 40 μm .

Claim 3 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein said synthetic resin film is formed from an aromatic polyimide, a polyamide, a polyamideimide, a polyethylene naphthalate, a polytetrafluoroethylene (PTFE), or a copolymer of tetrafluoroethylene and a perfluoroalkylvinyl ether.

Claim 4 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein said synthetic resin film has a melting point of 200°C or higher.

Claim 5 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein the thickness of each of said outer layers is within a range from 30 to 800 μm .

Claim 6 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein said organopolysiloxane of said component (a) is represented by an average composition formula $\text{R}^1_a\text{SiO}_{(4-a)/2}$ (wherein, R^1 are each independently a substituted or unsubstituted monovalent hydrocarbon group of 1 to 10 carbon atoms, which are the same or different, and a is a positive number of 1.90 to 2.05).

Claim 7 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein said organopolysiloxane of said component (a) has a backbone chain that comprises dimethylsiloxane units, or a backbone chain that comprises dimethylsiloxane units but a portion of the methyl groups are substituted with a vinyl group, a phenyl group, or a 3,3,3-trifluoropropyl group, and the molecular chain terminals of the backbone chain are blocked with a triorganosilyl group or a hydroxyl group.

Claim 8 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein the degree of polymerization of said component (a) is within a range from 200 to 12,000.

Claim 9 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein said curing agent of said component (b) comprises an organohydrogenpolysiloxane with an average of at least 2 hydrogen atoms bonded to silicon

atoms within a single molecule, and a platinum catalyst, and said organopolysiloxane of said component (a) is an organopolysiloxane that contains at least 2 alkenyl groups bonded to silicon atoms within a single molecule.

Claim 10 (Original): The heat conductive silicone rubber composite sheet according to claim 9, wherein the quantity of said organohydrogenpolysiloxane is a quantity such that the quantity of hydrogen atoms bonded to silicon atoms within said component (b) is from 0.1 to 4.0 mols per 1 mol of alkenyl groups bonded to silicon atoms within said component (a).

Claim 11 (Original): The heat conductive silicone rubber composite sheet according to claim 9, wherein the quantity of said platinum catalyst is a quantity such that the quantity of the platinum metal within said component (b) relative to the quantity of said component (a) is within a range from 0.01 to 1,000 ppm (by weight).

Claim 12 (Canceled):

Claim 13 (Previously Presented): The heat conductive silicone rubber composite sheet according to claim 1, wherein the quantity of said organic peroxide is within a range from 0.1 to 5 parts by weight per 100 parts by weight of said organopolysiloxane of said component (a).

Claim 14 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein said heat conductive filler of said component (c) comprises an inorganic powder.

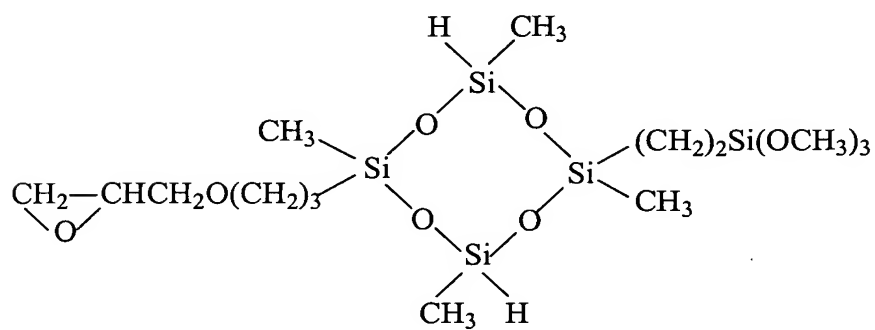
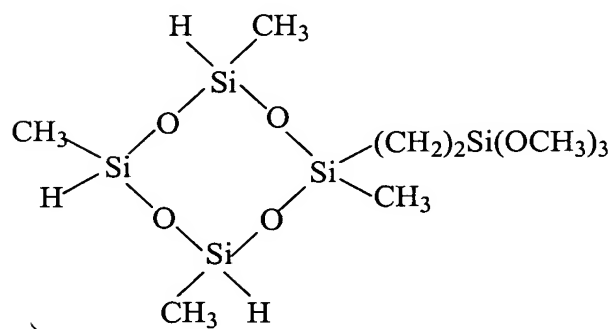
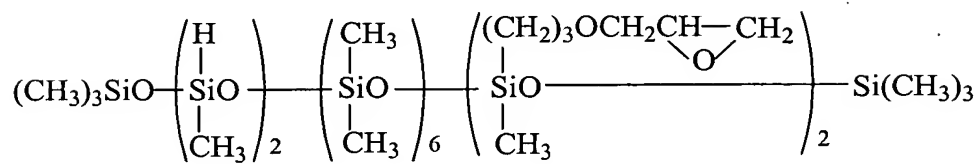
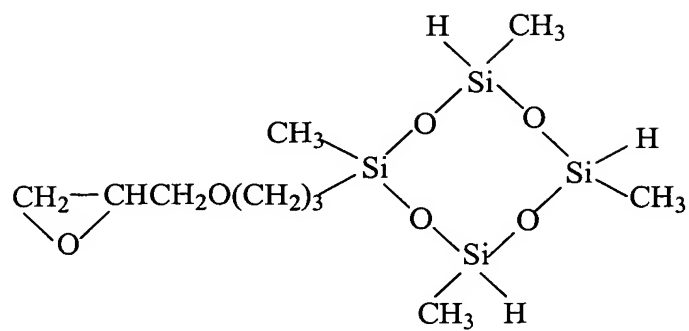
Claim 15 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein the average particle diameter of said component (c) is no more than 50 μm .

Claim 16 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein the quantity of said heat conductive filler of said component (c) is within a range from 100 to 1,800 parts by weight per 100 parts by weight of said organopolysiloxane of said component (a).

Claim 17 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein said silicon compound-based adhesion imparting agent of said component (d) has at least 2 functional groups which are each selected from the group consisting of epoxy groups, alkoxy groups, vinyl groups, and the group represented by the formula Si-H .

Claim 18 (Original): The heat conductive silicone rubber composite sheet according to claim 1, wherein the quantity of said component (d) is within a range from 0.1 to 3.0 parts by weight per 100 parts by weight of said component (a).

Claim 19 (Previously Presented): The heat conductive silicone rubber composite sheet according to claim 1, wherein said component (d) comprises at least one compound selected from the group consisting of:



, and

